

13. (Amended) A circuit board produced by the process of:

preparing a substrate having a joining surface;

D1 disposing a plurality of masses of solder paste on the joining surface of the substrate;

heating and melting the masses of solder paste, thereby forming the masses of solder paste into a plurality of solder bumps on the joining surface of the substrate; and

flattening and levelling tops of the solder bumps, thereby making smaller a coplanarity of the solder bumps.

19. (Amended) A circuit board according to claim 13, wherein circular pads are interposed between the respective solder bumps and the substrate, the tops of the solder bumps are nearly equal in diameter to the pads, and the height of the solder bumps is smaller than the diameter of the pads.

20. (Amended) A circuit board produced by the process of:

D2 preparing a substrate having a joining surface;

disposing a plurality of masses of solder paste on the joining surface of the substrate;

disposing a jig so that a flat surface of the jig is located at a predetermined position above the masses of solder paste; and

heating and melting the masses of solder paste to bring tops of the masses of solder paste into contact with the flat surface of the jig, thereby forming the masses of solder paste into solder bumps having tops that are flattened and leveled in such a way as to make smaller a coplanarity of the solder bumps.

P3 24. (Amended) A method of producing a circuit board comprising:

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preparing a substrate having a joining surface;

disposing of a plurality of masses of solder paste on the joining surface of the substrate;

heating and melting the masses of solder paste, thereby forming the masses of solder paste into a plurality of solder bumps on the joining surface of the substrate; and

flattening and levelling tops of the solder bumps thereby making smaller a coplanarity of the solder bumps.

28. (Amended) A method of producing a circuit board comprising:

preparing a substrate having a joining surface;

disposing a plurality of masses of solder paste on the joining surface of the substrate;

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disposing a jig so that a flat surface of the jig is located at a predetermined position above the masses of solder paste; and

heating and melting the masses of solder paste to bring tops of the masses of solder paste into contact with the flat surface of the jig, thereby forming the masses of solder paste into solder bumps having tops that are flattened and leveled in such a way as to make smaller a coplanarity of the solder bumps.

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29. (New)A circuit board according to claim 13, wherein the joining surface of the substrate has at least one curved portion in which at least one of the plurality of solder bumps is disposed on the at least one curved portion, and

wherein, prior to the flattening and levelling step, tops of the plurality of solder bumps are not coplanar with each other due at least in part to the at least one curved portion.

30. (New)A circuit board according to claim 20, wherein the joining surface of the substrate has at least one curved portion in which at least one of the plurality of solder bumps is disposed on the at least one curved portion, and

wherein, prior to the heating and melting step, tops of the plurality of solder bumps are not coplanar with each other due at least in part to the at least one curved portion.

31. (New)A method according to claim 24, wherein the joining surface of the substrate has at least one curved portion in which at least one of the plurality of solder bumps is disposed on the at least one curved portion, and

wherein, prior to the flattening and levelling step, tops of the plurality of solder bumps are not coplanar with each other due at least in part to the at least one curved portion.

32. (New)A method according to claim 28, wherein the joining surface of the substrate has at least one curved portion in which at least one of the plurality of solder bumps is disposed on the at least one curved portion, and

wherein, prior to the heating and melting step, tops of the plurality of solder bumps are not coplanar with each other due at least in part to the at least one curved portion.

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33. (New) A method according to claim 28, wherein in the step of disposing a jig, the flat surface of the jig is positioned such that the flat surface of the jig is not in contact with any of the masses of solder paste.
